# **HIGHER NITEC IN ELECTRONICS ENGINEERING (3 YEARS)**

#### **Foundation Modules**

# **Electrical & Cabling Technology**

On completion of the module, students should be able to set up, maintain and troubleshoot cabling systems.

### **CAD & Soldering**

On completion of the module, students should be able to create and update CAD drawings, as well as build electronic prototypes.

# **Digital Electronics**

On completion of the module, students should be able to set up and test digital electronic circuits.

# **Analogue Electronics**

On completion of the module, students should be able to set up and test analogue electronic circuits.

# **Programming Fundamentals**

On completion of the module, students should be able to apply programming constructs such as variables, programming syntax, sequential programming and control flow statements, in a programmable controller-based system.

#### **IoT Fundamentals**

On completion of the module, students should be able to configure, establish communication and process data from IoT environmental elements such as devices, nodes, gateways and cloud.

# **Networking & Communications Fundamentals**

On completion of the module, students should be able to set up, configure, maintain and test computer and communication networks. They should also be able to identify the various network topologies and protocols, and troubleshoot network connectivity faults.

# **Cybersecurity Fundamentals**

On completion of the module, students should be able to apply the knowledge and essentials skills in all security domains in the cyber world - information security, systems security, network security, mobile security, physical security, ethics and laws, related technologies, defence and mitigation techniques use in protecting.

#### **Core Modules**

#### **Electronic Devices & Circuits**

On completion of the module, students should be able to construct and test analogue electronic devices and circuits.

#### **Digital Electronics & Simulation**

On completion of the module, students should be able to test and troubleshoot various digital electronic circuits.

# **Analogue Applications**

On completion of the module, students should be able to analyse, test and troubleshoot analogue electronic applications.

# **Digital Applications**

On completion of the module, students should be able to analyse, construct, test and troubleshoot digital electronic applications.

# **Computer Networking**

On completion of the module, students should be able to set up computer network, troubleshoot network connectivity issues, as well as test network performance.

# **Microcontroller Applications**

On completion of the module, students should be able to create algorithms and develop microcontroller applications with input and output devices.

#### **Wireless Communications**

On completion of the module, students should be able to set up and test electronic communication systems.

### **Industry Attachment 1**

Students will undergo 3-month industry attachment to reinforce the skills and knowledge acquired at the training institute and to develop competencies in other areas not covered in the curriculum.

# **Specialisation Modules**

# **Group A (Audio Visual Systems)**

### **AV Peripherals**

On completion of the module, students should be able to integrate AV devices with peripherals and accessories, as well as align AV equipment.

# **AV Control & Automation**

On completion of the module, students should be able to install, configure, maintain and troubleshoot AV devices for network automation system.

### **AV** Integration

On completion of the module, students should be able to design, install, test and troubleshoot an AV system for an application.

# **AV IT & Streaming**

On completion of the module, students should be able to set up and configure networking devices for streaming network systems.

### **Industry Attachment 2**

Students will undergo 6-month industry attachment to reinforce the skills and knowledge acquired at the training institute and to develop competencies in other areas not covered in the curriculum.

# **Group B (IoT & Communications)**

#### **Sensors & Actuators**

On completion of the module, students should be able to identify applications and perform installation of sensors and output devices.

### **IoT Protocols & Power Management**

On completion of the module, students should be able to install, interface and configure sensors and output devices with controller to establish network communication.

# **IoT Programming & Cloud Services**

On completion of the module, students should be able to apply programming skills with knowledge of embedded system, as well as principles of cloud computing and IoT systems.

# IoT Data Analytics & Visualisation

On completion of the module, students should be able to perform data visualisation and analysis for an IoT application by applying business intelligence.

# **Industry Attachment 2**

Students will undergo 6-month industry attachment to reinforce the skills and knowledge acquired at the training institute and to develop competencies in other areas not covered in the curriculum.

### **Group C (AI & Automation)**

#### Al Fundamentals

On completion of the module, students should be able to perform various Machine Learning (ML) tasks by applying ML libraries and frameworks.

# **Al Applications**

On completion of the module, students should be able to solve real-world applications by applying Al services and technologies.

# Principles of Autonomous Robotic System

On completion of the module, students should be able to deploy and test autonomous systems, as well as perform localisation, mapping and navigation by applying robotic algorithms.

### **Autonomous System Applications**

On completion of the module, students should be able to deploy and troubleshoot autonomous systems, by applying principles of perception, planning, localising, mapping and decision-making capabilities.

# **Industry Attachment 2**

Students will undergo 6-month industry attachment to reinforce the skills and knowledge acquired at the training institute and to develop competencies in other areas not covered in the curriculum.

### **Group D (Microelectronics)**

#### Semiconductor Fundamentals

On completion of the module, students should be able to perform cleanroom and safety protocols, and maintain vacuum systems.

### **Semiconductor Processes**

On completion of the module, students should be able to perform automated wafer processes for fabrication of integrated circuits used in electronic devices.

### Semiconductor Metrology

On completion of the module, students should be able to perform semiconductor metrology measurements for fabrication of integrated circuits processes.

# **Industrial Automation**

On completion of the module, students should be able to implement electro-mechanical control systems, including common input/output devices, pneumatics, electro-pneumatics and Programmable Logic Controller (PLC) systems in industrial automation.

# **Industry Attachment 2**

Students will undergo 6-month industry attachment to reinforce the skills and knowledge acquired at the training institute and to develop competencies in other areas not covered in the curriculum.